

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMS/20/11886	
1.3 Title of PCN	New molding compound for DIP package to replace SAMSUNG SDI under termination phase	
1.4 Product Category	See product list	
1.5 Issue date	2020-01-28	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Domenico ARRIGO,Marcello SAN BIAGIO
2.1.2 Marketing Manager	Salvatore DI VINCENZO,Fulvio PULICELLI
2.1.3 Quality Manager	Sergio Tommaso SPAMPINATO,Alessandro PLATINI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	Assembly = Nantong Fujitsu (China)

4. Description of change

	Old	New
4.1 Description	Molding compound = Samsung SG8200DTA	Molding compound = Replacement of current molding compounds with alternative material from different supplier (see qualification report for more details)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	As stated in the ST Corporate Product Change Information CRP/19/11478, the current molding compound supplied by Samsung will be terminated. So the goal of this PCN is to announce the qualification of a new molding compound for products in DIP package assembled in Nantong Fujitsu (China). The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet. There is no change in the packing modes and the standard delivery quantities either.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	New Finished good codes
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7. Timing / schedule

7.1 Date of qualification results	2019-12-15
7.2 Intended start of delivery	2020-05-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11886 Qual report.zip
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2020-01-28
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9. Attachments (additional documentations)			
11886 Public product.pdf 11886 Qual report.zip			

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
AVS1ACP08	AVS1ACP08	
L4971	L4971	
L4978	L4978	
L6561	L6561	
	L6562AN	
L6562N	L6562N	
MC34063ABN	MC34063ABN	
MC34063EBN	MC34063EBN	
497-4280-5-ND	MC34063ECN	
MC34063ECN	MC34063ECN	
	TDE1798DP	
	UC2844BN	
	UC2845BN	
	UC3842BN	
	UC3843BN	
	UC3844BN	
	UC3845BN	
	VIPER06HN	
	VIPER06LN	
	VIPER06XN	
	VIPER16HN	
	VIPER17HN	
	VIPER17LN	
	VIPER26HN	
	VIPER26LN	
	VIPER27HN	
	VIPER27LN	
	VIPER28HN	
	VIPER35HE	
	VIPER35LE	
	VIPER37HE	
	VIPER37LE	
	VIPER38HE	
	VIPER38LE	
	VIPER28LN	

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Public Products List

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PCN Title : New molding compound for DIP package to replace SAMSUNG SDI under termination phase

PCN Reference : AMS/20/11886

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

VIPER16HN	VIPER35LE	VIPER38LE
MC34063ABN	MC34063ACN	UC2844BN
UC3842BN	L4978	TDE1798DP
UC3843BN	L4971	VIPER26LN
VIPER37LE	UC2843BN	VIPER17HN
L4976	VIPER25LN	VIPER28LN
VIPER27HN	VIPER38HE	VIPER27LN
L6565N	VIPER28HN	VIPER06HN
MC34063EBN	MC34063ECN	UC3844BN
VIPER26HN	UC2845BN	VIPER06LN
VIPER06XN	VIPER17LN	UC2842BN
VIPER25HN	UC3845BN	VIPER35HE
L6562AN	L6561	L6562N
VIPER37HE		



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